

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit		
STATIC ELECTRICAL RATINGS							
BV_{DSS}	Drain – Source Breakdown Voltage	$V_{GS} = 0$	$I_D = 1\text{mA}$	400	V		
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	Reference to 25°C $I_D = 1\text{mA}$		0.46	$\text{V}/^\circ\text{C}$		
$R_{DS(on)}$	Static Drain – Source On–State Resistance ⁴	$V_{GS} = 10\text{V}$	$I_D = 6\text{A}$		0.55		
		$V_{GS} = 10\text{V}$	$I_D = 10\text{A}$		0.70		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250\mu\text{A}$	2	4		
g_{fs}	Forward Transconductance ⁴	$V_{DS} \geq 15\text{V}$	$I_{DS} = 6\text{A}$	4.9	$\text{S}(\bar{v})$		
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0$	$V_{DS} = 0.8BV_{DSS}$ $T_J = 125^\circ\text{C}$		25		
					250		
I_{GSS}	Forward Gate – Source Leakage	$V_{GS} = 20\text{V}$			100		
I_{GSS}	Reverse Gate – Source Leakage	$V_{GS} = -20\text{V}$			-100		
DYNAMIC CHARACTERISTICS							
C_{iss}	Input Capacitance	$V_{GS} = 0$		1400	pF		
C_{oss}	Output Capacitance	$V_{DS} = 25\text{V}$		3500			
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		2300			
Q_g	Total Gate Charge ¹	$V_{GS} = 10\text{V}$	$I_D = 10\text{A}$		32		
Q_{gs}	Gate – Source Charge ¹			$V_{DS} = 0.5BV_{DSS}$		2.2	
Q_{gd}	Gate – Drain (“Miller”) Charge ¹					13.8	
$t_{d(on)}$	Turn–On Delay Time				2.5		
t_r	Rise Time	$V_{DD} = 200\text{V}$	$I_D = 10\text{A}$		92		
$t_{d(off)}$	Turn–Off Delay Time			$R_G = 9.1\Omega$	$V_{GS} = 10\text{V}$		79
t_f	Fall Time						
SOURCE – DRAIN DIODE CHARACTERISTICS							
I_S	Continuous Source Current				10		
I_{SM}	Pulse Source Current ¹				40		
V_{SD}	Diode Forward Voltage ⁴	$I_S = 10\text{A}$	$T_J = 25^\circ\text{C}$		1.5		
t_{rr}	Reverse Recovery Time ⁴	$I_F = 10\text{A}$	$T_J = 25^\circ\text{C}$		600		
Q_{rr}	Reverse Recovery Charge ⁴	$d_i / d_t \leq 100\text{A}/\mu\text{s}$		$V_{DD} \leq 50\text{V}$	5.6		
t_{on}	Forward Turn–On Time			Negligible			
PACKAGE CHARACTERISTICS							
L_D	Internal Drain Inductance (from centre of drain pad to die)			2.0	nH		
L_S	Internal Source Inductance (from centre of source pad to end of source bond wire)			6.5			